

# SOT804-8(DD)

HVQFN64, Thermal enhanced very thin quad flat package; no leads; 64 terminals; 0.5 mm pitch, 9 mm x 9 mm x 0.9 mm body

25 July 2023

Package information



## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN64
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-12-2022
<b>Manufacturer package code</b>	98ASA02024D

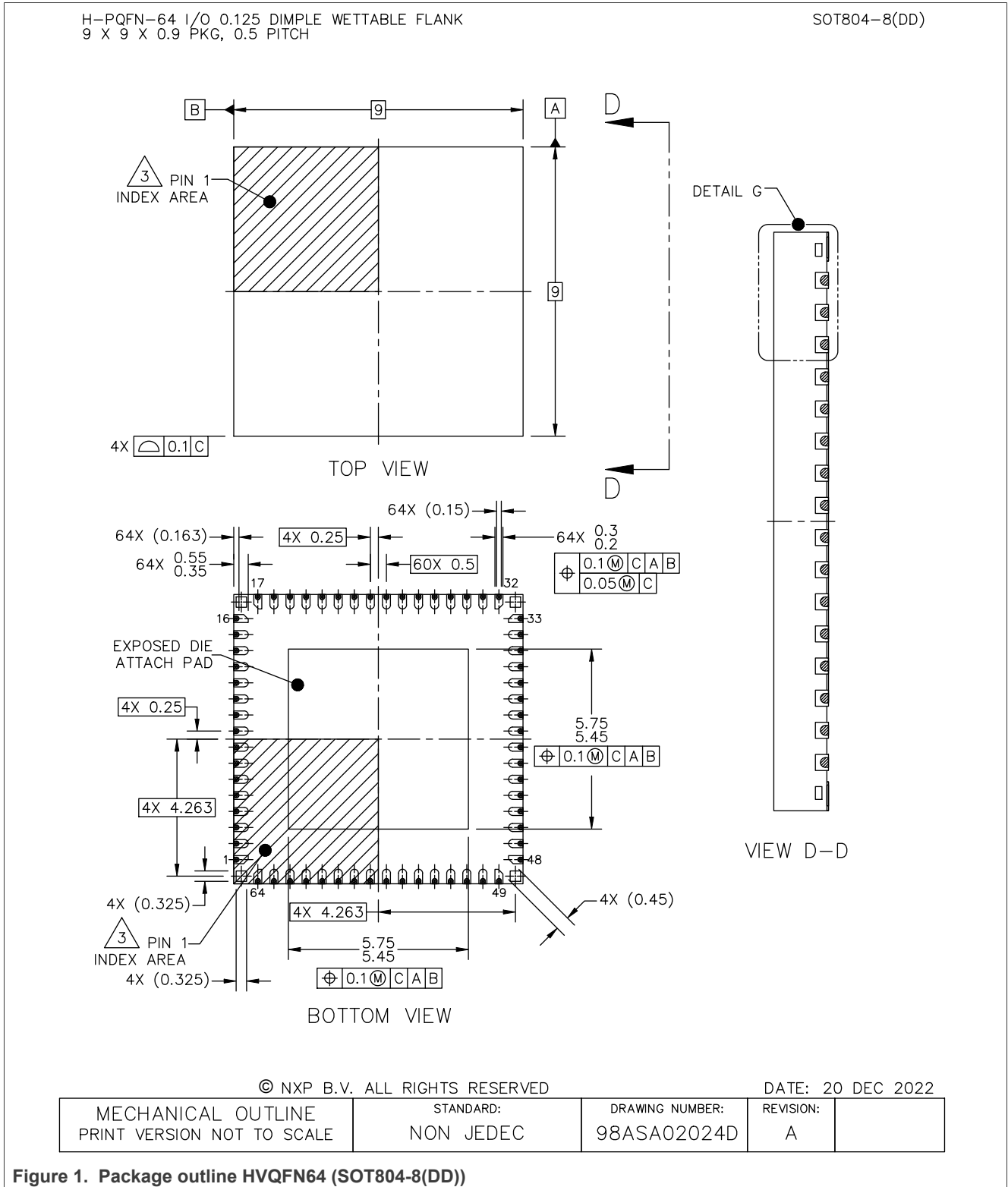
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.9	9	9.1	mm
package width	8.9	9	9.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	



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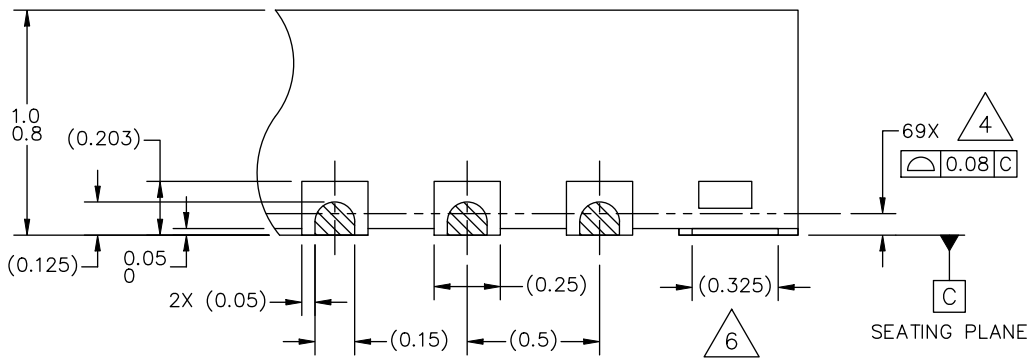
2 Package outline



HVQFN64, Thermal enhanced very thin quad flat package; no leads; 64 terminals; 0.5 mm pitch, 9 mm x 9 mm x 0.9 mm body

H-PQFN-64 I/O 0.125 DIMPLE WETTABLE FLANK  
9 X 9 X 0.9 PKG, 0.5 PITCH

SOT804-8(DD)



DETAIL E  
VIEW ROTATED 90° CW

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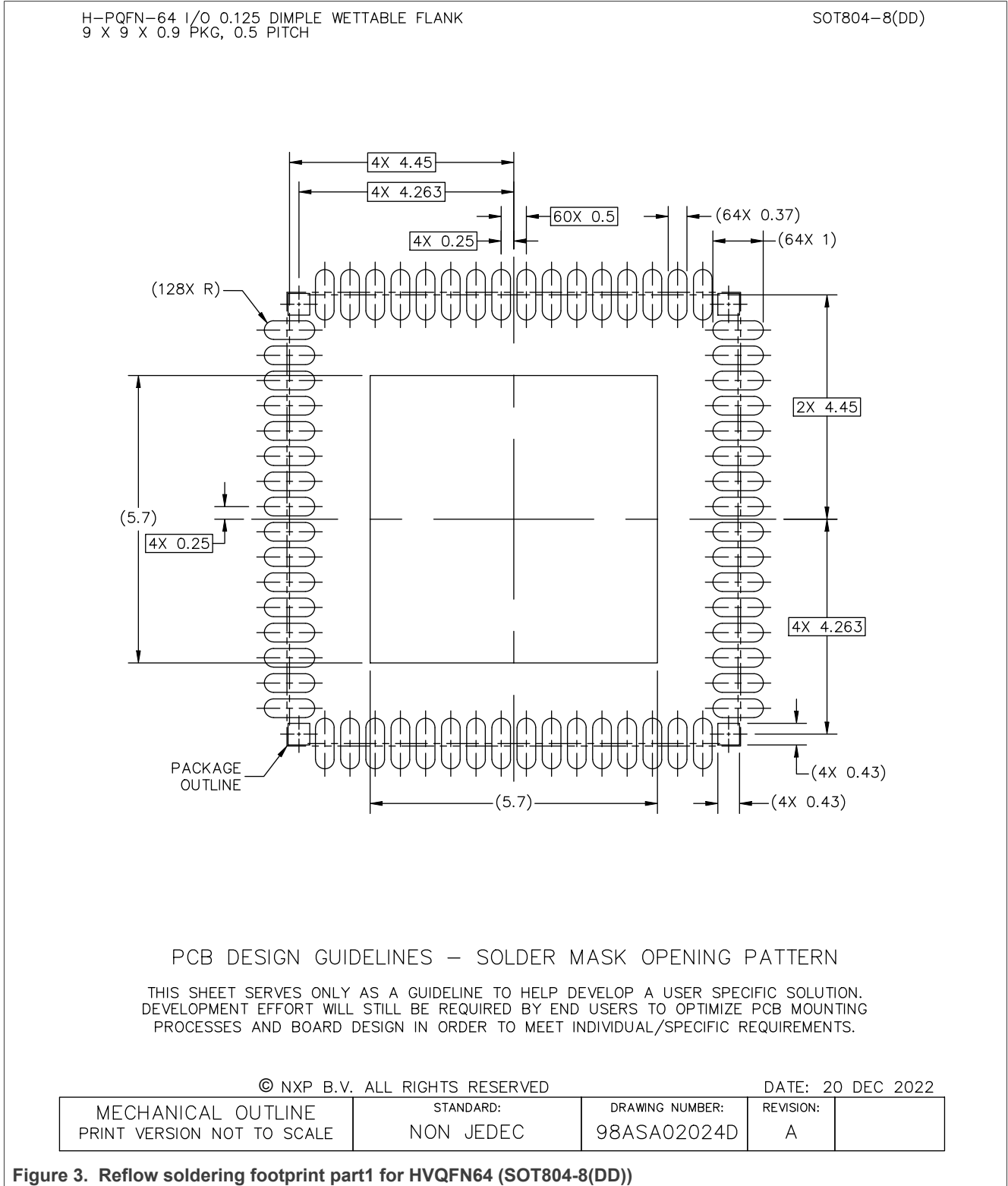
DATE: 20 DEC 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02024D	REVISION: A	
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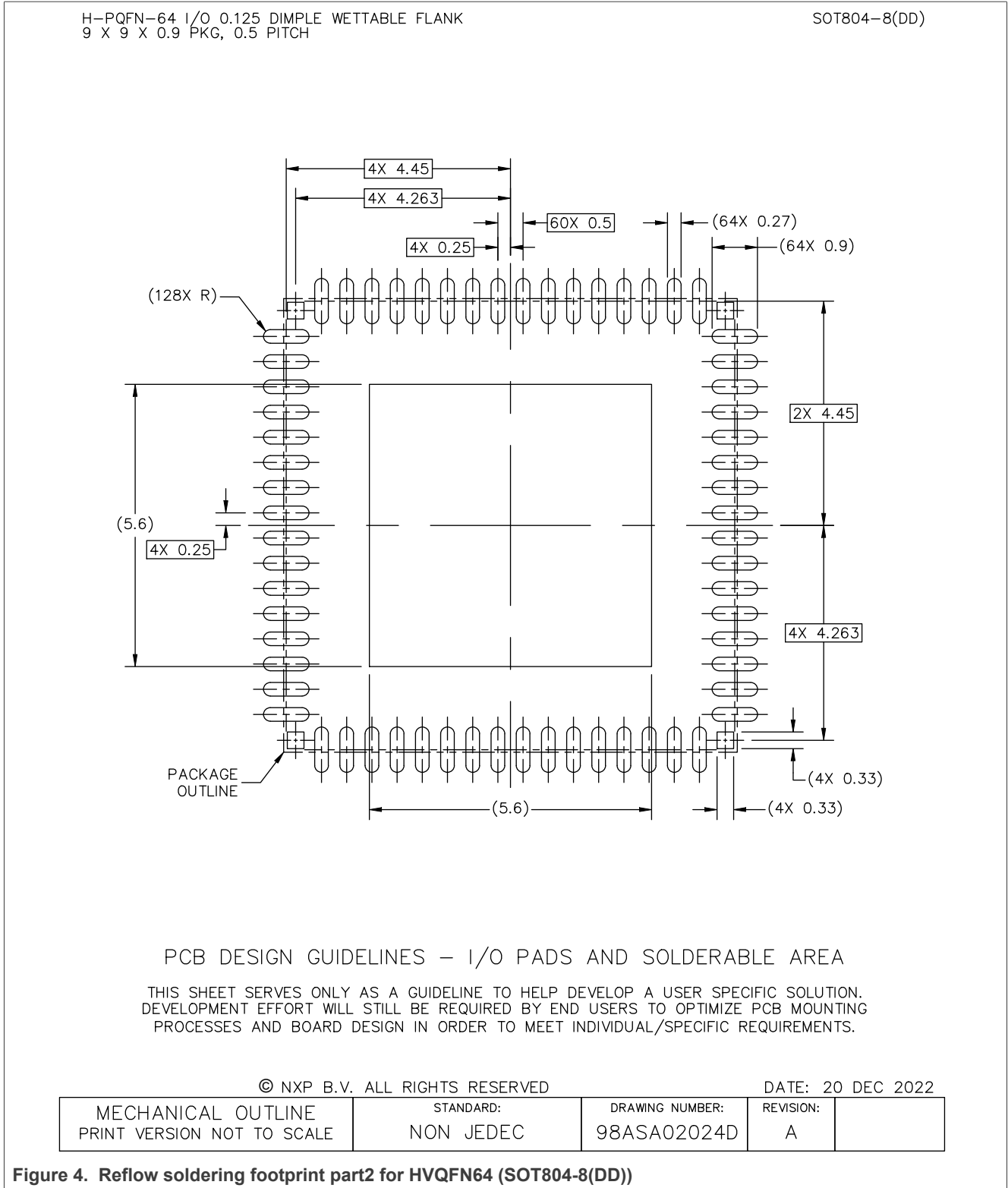
Figure 2. Package outline detail E of HVQFN64 (SOT804-8(DD))

HVQFN64, Thermal enhanced very thin quad flat package; no leads; 64 terminals; 0.5 mm pitch, 9 mm x 9 mm x 0.9 mm body

3 Soldering



HVQFN64, Thermal enhanced very thin quad flat package; no leads; 64 terminals; 0.5 mm pitch, 9 mm x 9 mm x 0.9 mm body



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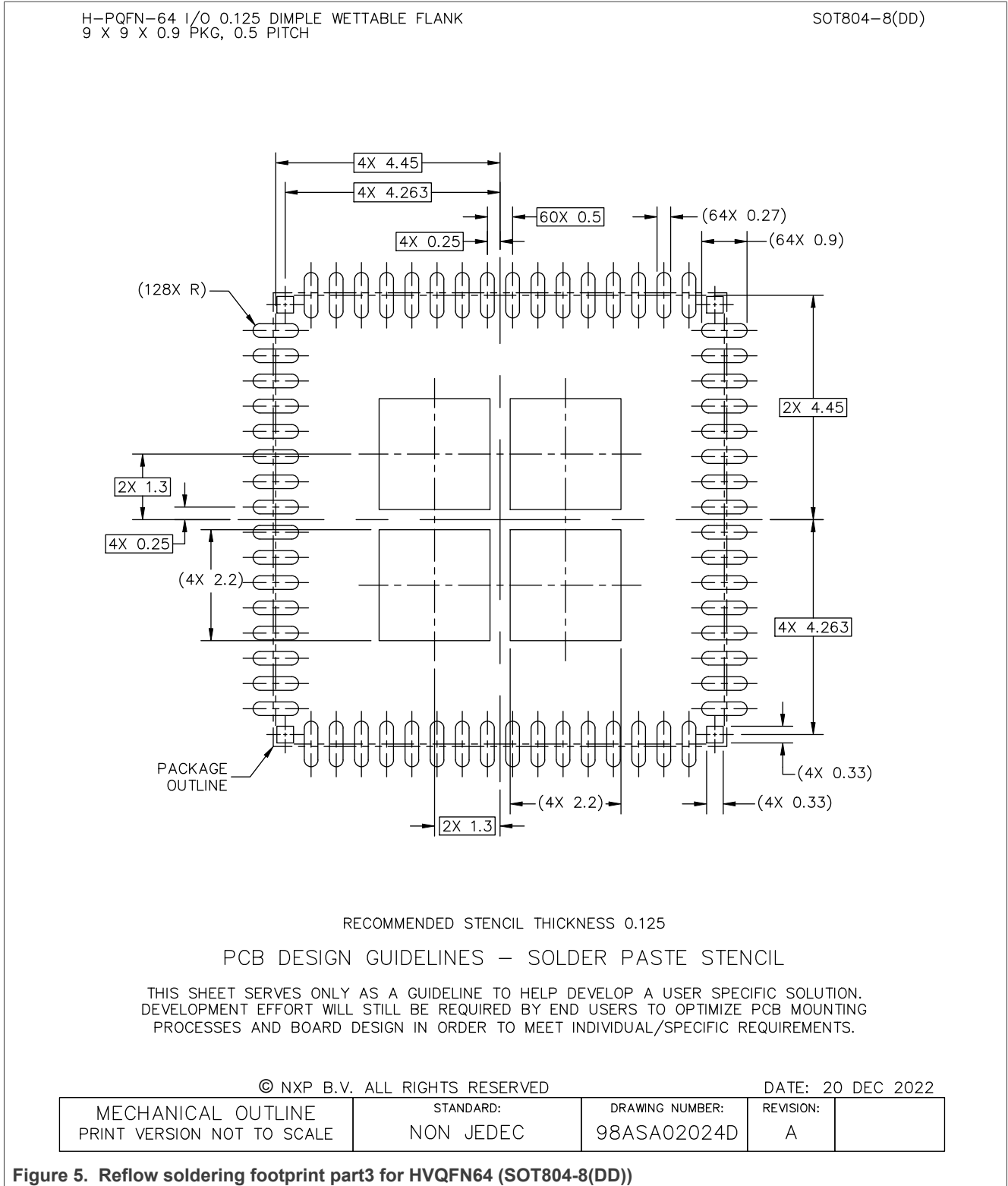


Figure 5. Reflow soldering footprint part3 for HVQFN64 (SOT804-8(DD))

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H-PQFN-64 I/O 0.125 DIMPLE WETTABLE FLANK  
9 X 9 X 0.9 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note HVQFN64 (SOT804-8(DD))

## 4 Legal information

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